













- ► THT Through hole
- ▶ 8.0x4.2x5.2mm
- ► Photo Interrupter (PI)

N0P71L02



THT Photo Interrupter





DESCRIPTION:

- Compact package based on the double-mould method.
- High resolution (slit width = 0.5mm).
- Gap between emitter and detector is 4.0mm.

THT Photo Interrupter

APPLICATIONS:

- Floppy Disk Drives
- **Printers**
- Cameras

FEATURES:

- Package: THT 4-Pins Photo Interrupter Block
- **Maximum Forward Current: 50mA**
- Peak Forward Voltage (typ.): 3V
- Infrared Peak Wavelength (typ.): 950nm
- Wavelength of Maxi. Sensitivity (typ.): 800nm
- **Operating Temperature: -25~+85°C**
- Storage Temperature: -40~+100°C
- Soldering methods: Hand; Soldering Heat (DIP)
- Packing: Bulk in Carton



CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter		Symbol	Ratings	Unit
Input	Forward Current	IF	50	mA
	Reverse Voltage	V _R	5	V
	Power Dissipation	P _D	80	mW
Output	Collector-Emitter Voltage	V _{CEO}	30	V
	Emitter-Collector Voltage	V _{ECO}	4.5	V
	Collector Current	Ic	30	mA
	Collector Power Dissipation	Pc	80	mW
Operating Temperature		T _{OPR}	-25~+85	°C
Storage Temperature		T _{STG}	-40~+100	°C
Soldering Temperature		TsoL	260 for 10s	°C



CHARACTERISTICS:

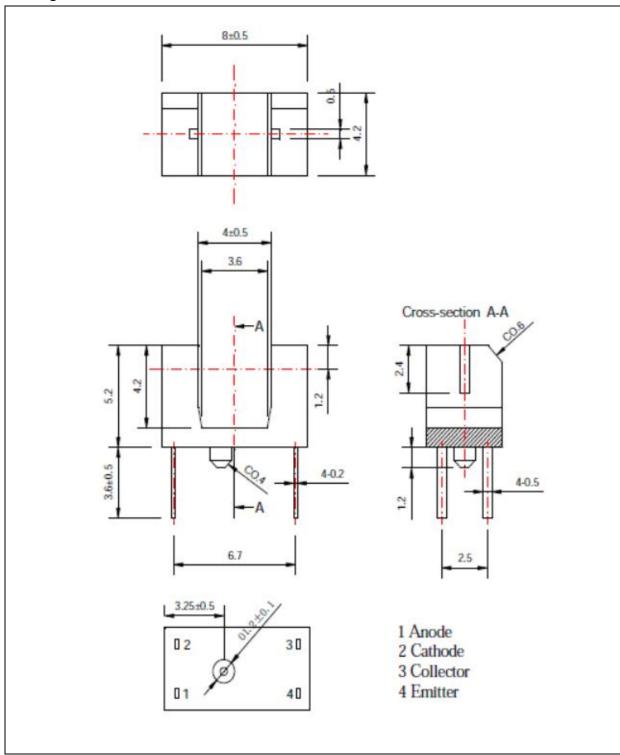
Electrical & Optical Characteristics (T_a=25°C)

Parameter		Constant	Values				Test
		Symbol	Min.	Тур.	Max.	Unit	Condition
Input	Forward Voltage	V _F		1.3	1.6	V	I _F =50mA
	Peak Forward Voltage	V _{FM}		3	4	V	I _{FM} =0.5A
	Reverse Current	I _R			10	μΑ	V _R =5V
	Collector Dark Current	I _{CEO}			0.5	μΑ	V _{ce} =10V
Output	Collector-Emitter Breakdown Voltage	BV _{CEO}	30			V	I _{ce} =50μA
	Emitter-Collector Breakdown Voltage	BV _{ECO}	4.5			V	I _{ec} =50μA
	Collector Current	Ic	0.2	0.55		mA	V _{ce} =5V I _F =20mA
Coupled	Collector-Emitter Saturation Voltage	V _{ce} (sat)			0.4	V	I _F =20mA I _c =0.1A
•	Response Time	T _r /T _f		10		μs	I_F =5mA V_{cc} =5V R_L =100 Ω
Infrared	Cut-off Frequency	fc		1		MHz	I _F =50mA
LED	Peak Light Emitting Wavelength	λ_{P}		950		nm	
Photo Transistor	Response Time	T _r /T _f		10		μs	V_{cc} =5 V I_c =1 mA R_L =100 Ω
	Maximum Sensitivity Wavelength	λ_{P}		800		nm	



OUTLINE DIMENSION:

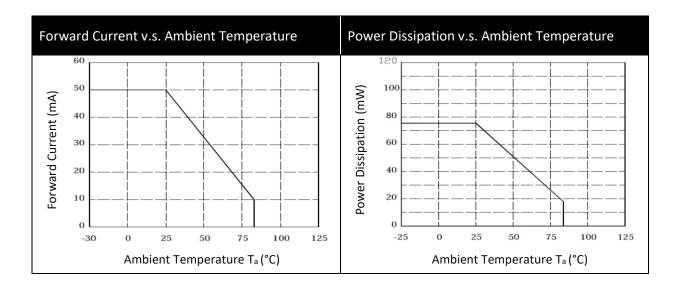
Package Dimension:

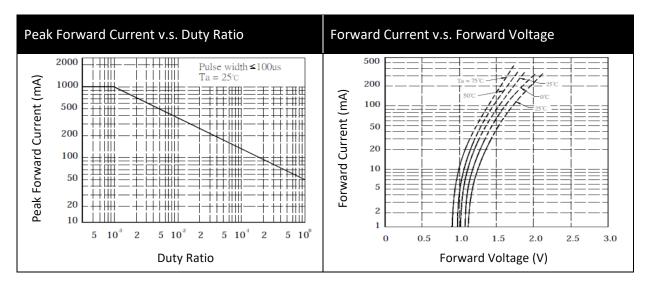


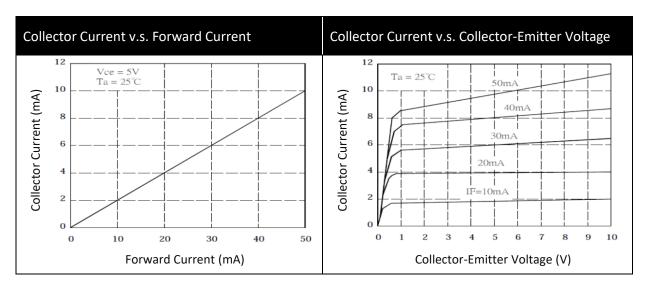
- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



ELECTRO-OPTICAL CHARACTERISTICS:

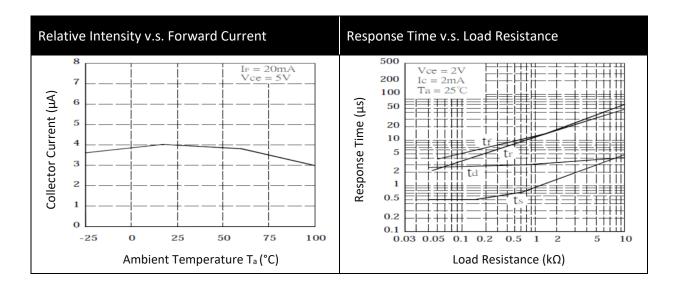


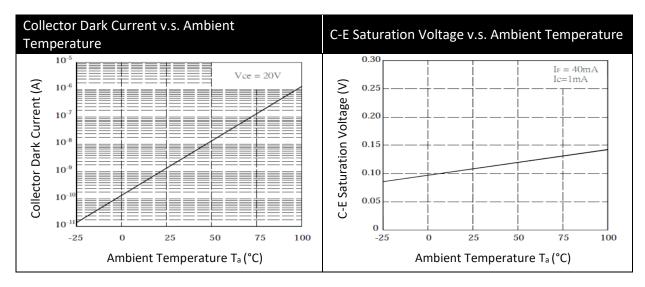


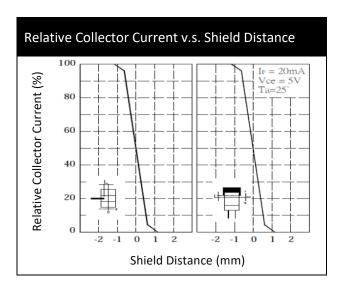




ELECTRO-OPTICAL CHARACTERISTICS:



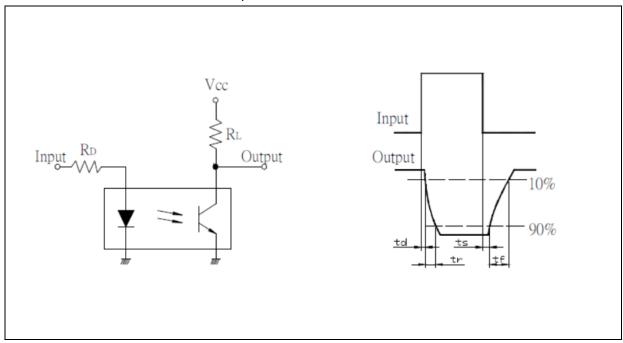






TEST CIRCUIT:

Test Circuit and Waveforms for Response Time:



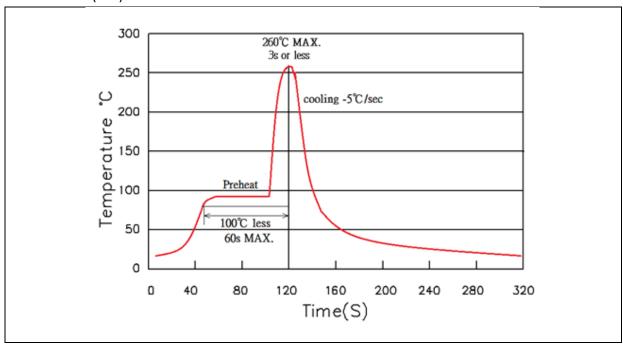


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Solder Heat (DIP):



Note:

- 1. Recommend reflow temperature 245°C. The maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 1 time.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

• Humidity: 60% R.H. Max.

• Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a year. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	22/07/2025	Datasheet set-up.